

74LVC16241A

16-bit buffer/line driver with 5 V tolerant inputs/outputs;
3-state

Rev. 4 — 26 October 2011

Product data sheet

1. General description

The 74LVC16241A is a 16-bit non-inverting buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs ($1OE$, $2OE$, $3OE$ and $4OE$). Schmitt trigger action at all inputs makes the circuit highly tolerant of slower input rise and fall times. The device can be used as four 4-bit buffers, two 8-bit buffers or one 16-bit buffer.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs. These features allow the use of these devices in mixed 3.3 V and 5 V applications.

2. Features and benefits

- 5 V tolerant inputs and outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- MULTIBYTE flow-through standard pin-out architecture
- Low inductance multiple power and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- High-impedance outputs when $V_{CC} = 0$ V
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115B exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C.



3. Ordering information

Table 1. Ordering information

Type number	Package				Version
	Temperature range	Name	Description		
74LVC16241ADL	-40 °C to +125 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm		SOT370-1
74LVC16241ADGG	-40 °C to +125 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm		SOT362-1

4. Functional diagram

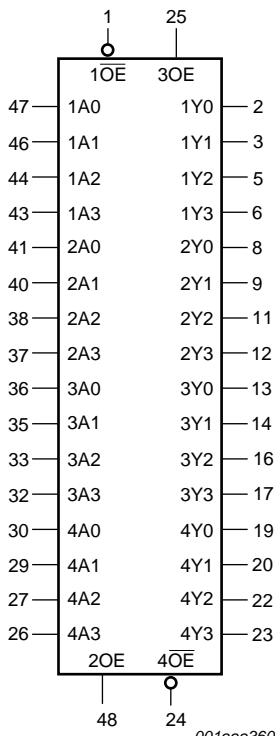


Fig 1. Logic symbol

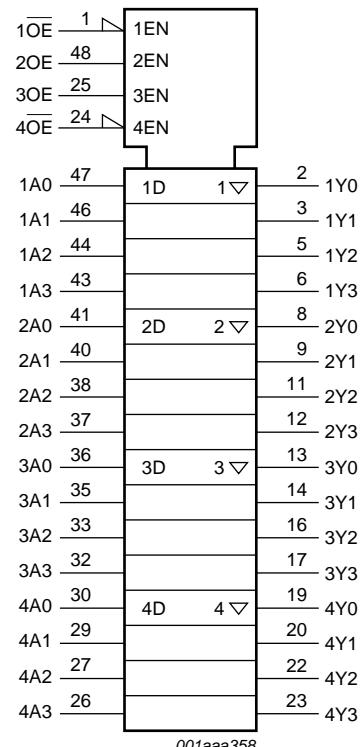


Fig 2. IEC logic symbol

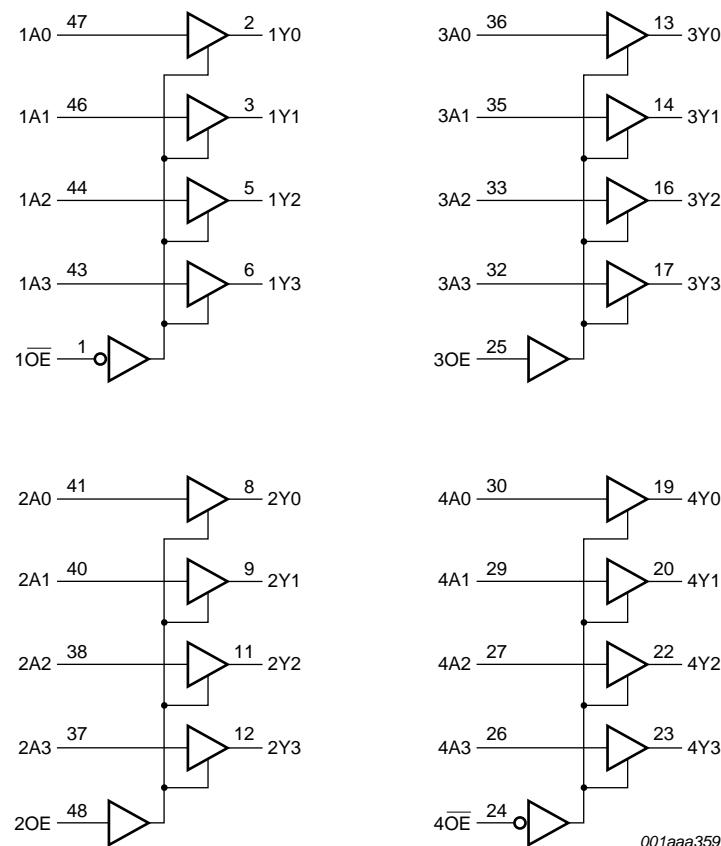


Fig 3. Logic diagram

5. Pinning information

5.1 Pinning

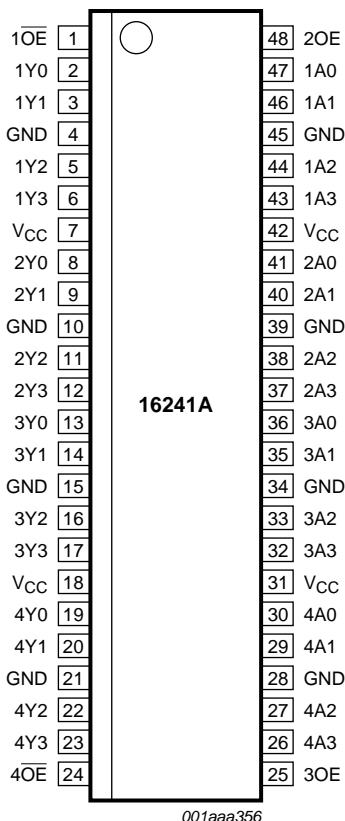


Fig 4. Pin configuration

5.2 Pin description

Table 2. Pin description

Name	Pin	Description
1OE	1	output enable input (active LOW)
2OE	48	output enable input (active HIGH)
3OE	25	output enable input (active HIGH)
4OE	24	output enable input (active LOW)
GND	4, 10, 15, 21, 28, 34, 39, 45	ground (0 V)
V _{CC}	7, 18, 31, 42	supply voltage
1Y[0:3]	2, 3, 5, 6	data output
2Y[0:3]	8, 9, 11, 12	data output
3Y[0:3]	13, 14, 16, 17	data output
4Y[0:3]	19, 20, 22, 23	data output
1A[0:3]	47, 46, 44, 43	data input

Table 2. Pin description ...continued

Name	Pin	Description
2A[0:3]	41, 40, 38, 37	data input
3A[0:3]	36, 35, 33, 32	data input
4A[0:3]	30, 29, 27, 26	data input

6. Functional description

Table 3. Function table^[1]

Input		Output	
nAn	nOE	nOE	nYn
H	L	-	H
	-	H	H
L	L	-	L
	-	H	L
X	H	-	Z
	-	L	Z

[1] H = HIGH voltage level

L = LOW voltage level

X = don't care

Z = high-impedance OFF-state

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage		[1]	-0.5	+6.5
I _{OK}	output clamping current	V _O > V _{CC} or V _O < 0 V	-	±50	mA
V _O	output voltage	HIGH or LOW state	[2]	-0.5	V _{CC} + 0.5
		3-state	[2]	-0.5	+6.5
I _O	output current	V _O = 0 V to V _{CC}	-	±50	mA
I _{CC}	supply current		-	100	mA
I _{GND}	ground current		-100	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	[3]	-	500
					mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] Above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V _I	input voltage		0	-	5.5	V
V _O	output voltage	HIGH or LOW state	0	-	V _{CC}	V
		3-state	0	-	5.5	V
T _{amb}	ambient temperature	in free air	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 1.65 V to 2.7 V	0	-	20	ns/V
		V _{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	0.65 × V _{CC}	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = -100 μA; V _{CC} = 1.65 V to 3.6 V	V _{CC} - 0.2	-	-	V _{CC} - 0.3	-	V
		I _O = -4 mA; V _{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I _O = -8 mA; V _{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I _O = -18 mA; V _{CC} = 3.0 V	2.4	-	-	2.25	-	V
V _{OL}	LOW-level output voltage	I _O = -24 mA; V _{CC} = 3.0 V	2.2	-	-	2.0	-	V
		V _I = V _{IH} or V _{IL}						
		I _O = 100 μA; V _{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.4	-	0.6	V
I _I	input leakage current	I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.55	-	0.8	V
		V _{CC} = 3.6 V; V _I = 5.5 V or GND	-	±0.1	±5	-	±20	μA

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 3.6$ V; $V_O = 5.5$ V or GND;	-	± 0.1	± 5	-	± 20	μA
I_{OFF}	power-off leakage current	$V_{CC} = 0$ V; V_I or $V_O = 5.5$ V	-	± 0.1	± 10	-	± 20	μA
I_{CC}	supply current	$V_{CC} = 3.6$ V; $V_I = V_{CC}$ or GND; $I_O = 0$ A	-	0.1	20	-	80	μA
ΔI_{CC}	additional supply current	per inputpin; $V_{CC} = 2.7$ V to 3.6 V; $V_I = V_{CC} - 0.6$ V; $I_O = 0$ A	-	5	500	-	5000	μA
C_I	input capacitance	$V_{CC} = 0$ V to 3.6 V; $V_I = GND$ to V_{CC}	-	5.0	-	-	-	pF

[1] All typical values are measured at $V_{CC} = 3.3$ V (unless stated otherwise) and $T_{amb} = 25$ °C.

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	$T_{amb} = -40$ °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t_{pd}	propagation delay	nAn to nYn; see Figure 5	[2]					
		$V_{CC} = 1.2$ V	-	13	-	-	-	ns
		$V_{CC} = 1.65$ V to 1.95 V	1.7	4.8	10.1	1.7	11.7	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.5	2.6	5.3	1.5	6.1	ns
		$V_{CC} = 2.7$ V	1.0	2.6	5.0	1.0	6.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	2.2	4.4	1.0	5.5	ns
t_{en}	enable time	nOE to nYn; see Figure 6	[2]					
		$V_{CC} = 1.2$ V	-	17	-	-	-	ns
		$V_{CC} = 1.65$ V to 1.95 V	1.0	5.2	12.5	1.0	13.2	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.0	3.0	6.9	1.0	7.3	ns
		$V_{CC} = 2.7$ V	1.0	3.2	6.0	1.0	7.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	2.4	5.5	1.0	7.0	ns
		nOE to nYn; see Figure 7						
		$V_{CC} = 1.2$ V	-	19	-	-	-	ns
		$V_{CC} = 1.65$ V to 1.95 V	2.5	6.9	14.2	2.5	15.0	ns
		$V_{CC} = 2.3$ V to 2.7 V	2.1	3.9	7.5	2.1	8.3	ns
		$V_{CC} = 2.7$ V	1.5	3.3	6.0	1.5	7.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.5	3.1	5.5	1.5	7.0	ns

Table 7. Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

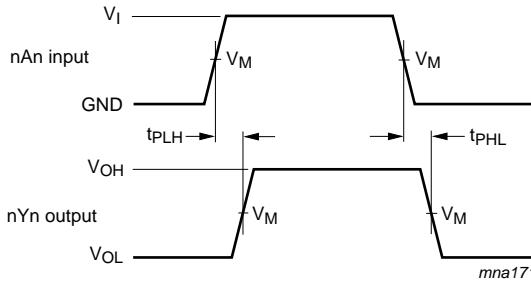
Symbol	Parameter	Conditions	T _{amb} = -40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	
t _{dis}	enable time	nOE to nYn; see Figure 6	[2]				
		V _{CC} = 1.2 V	-	9.0	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	2.4	4.3	8.3	2.4	9.2 ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.4	4.7	1.0	5.2 ns
		V _{CC} = 2.7 V	1.5	3.2	5.5	1.5	7.0 ns
		V _{CC} = 3.0 V to 3.6 V	1.5	3.0	5.0	1.5	6.5 ns
		nOE to nYn; see Figure 7					
		V _{CC} = 1.2 V	-	8.0	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	3.5	8.4	1.5	9.6 ns
		V _{CC} = 2.3 V to 2.7 V	0.5	1.9	4.8	0.5	5.5 ns
		V _{CC} = 2.7 V	1.5	3.5	5.5	1.5	7.0 ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.6	5.0	1.0	6.5 ns
C _{PD}	power dissipation capacitance	per input; V _I = GND to V _{CC}	[3]				
		V _{CC} = 1.65 V to 1.95 V	-	8.4	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	11.9	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	15.0	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.[2] t_{pd} is the same as t_{PLH} and t_{PHL}.t_{en} is the same as t_{PZL} and t_{PZH}.t_{dis} is the same as t_{PLZ} and t_{PHZ}.[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μ W). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:f_i = input frequency in MHz; f_o = output frequency in MHzC_L = output load capacitance in pFV_{CC} = supply voltage in Volts

N = number of inputs switching

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs

11. Waveforms

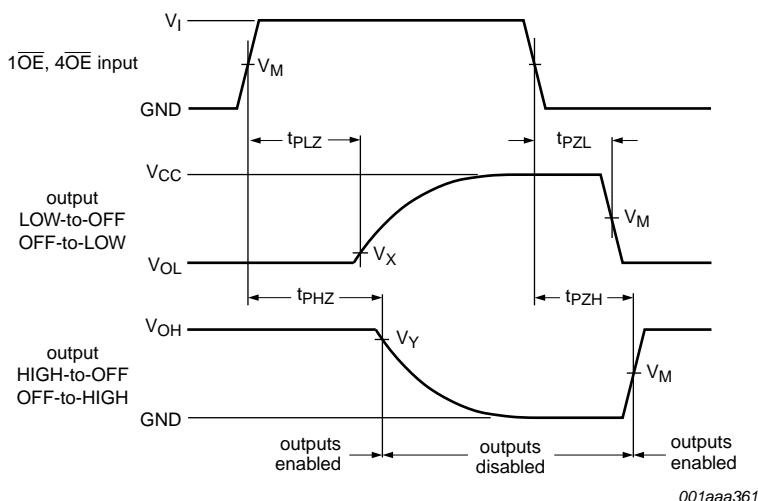


$V_M = 1.5 \text{ V at } V_{CC} \geq 2.7 \text{ V};$

$V_M = 0.5 \times V_{CC} \text{ at } V_{CC} < 2.7 \text{ V.}$

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. Input nAn to output nYn propagation delays



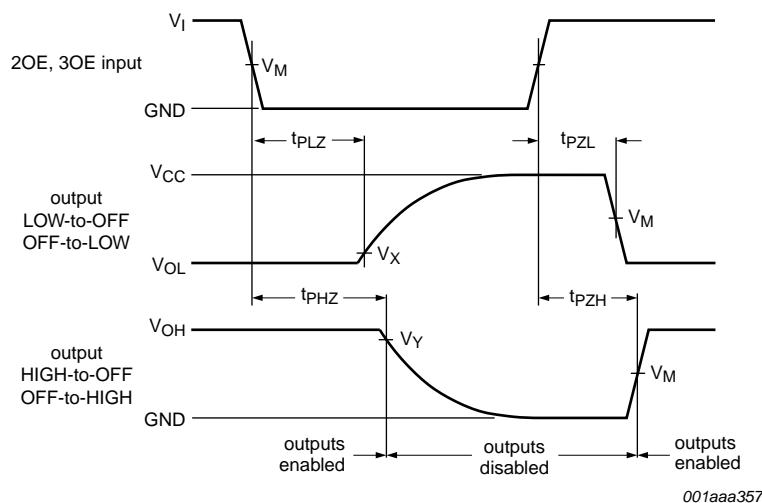
Measurements points are given in [Table 8](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. 3-state enable and disable times for inputs 1OE and 4OE

Table 8. Measurement points

Supply voltage	Input	Output		
V_{CC}	V_M	V_M	V_X	V_Y
1.2 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
3.0 V to 3.6 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



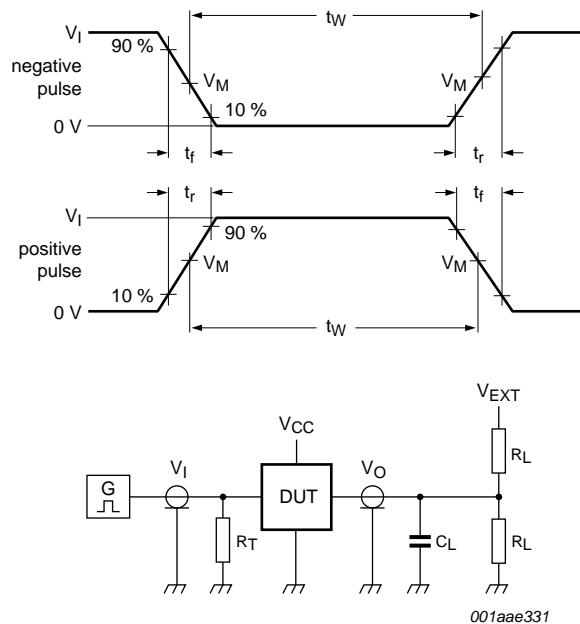
Measurements points are given in [Table 9](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. 3-state enable and disable times for inputs 2OE and 3OE

Table 9. Measurement points

Supply voltage	Input	Output		
V_{CC}	V_M	V_M	V_X	V_Y
1.2 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
3.0 V to 3.6 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_0 of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

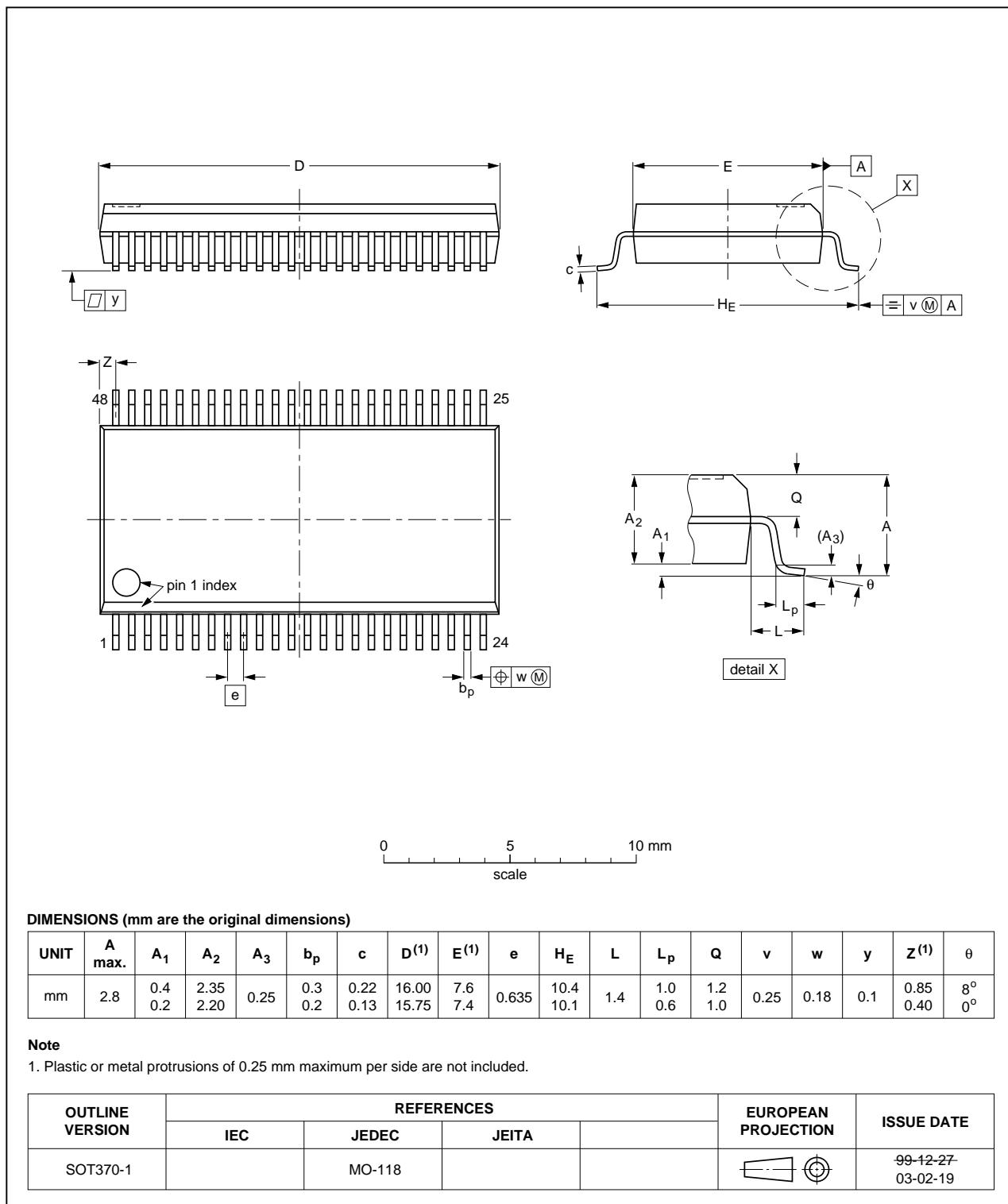
Table 10. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	$2 \times V_{CC}$	GND

12. Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.8	0.4	2.35	2.20	0.25	0.3	0.22	16.00	7.6	0.635	10.4	1.4	1.0	1.2	0.25	0.18	0.85	8°
		0.2		2.0		0.2	0.13	15.75	7.4		10.1		0.6	1.0		0.18	0.40	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT370-1		MO-118				99-12-27 03-02-19

Fig 9. Package outline SOT370-1 (SSOP48)

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1

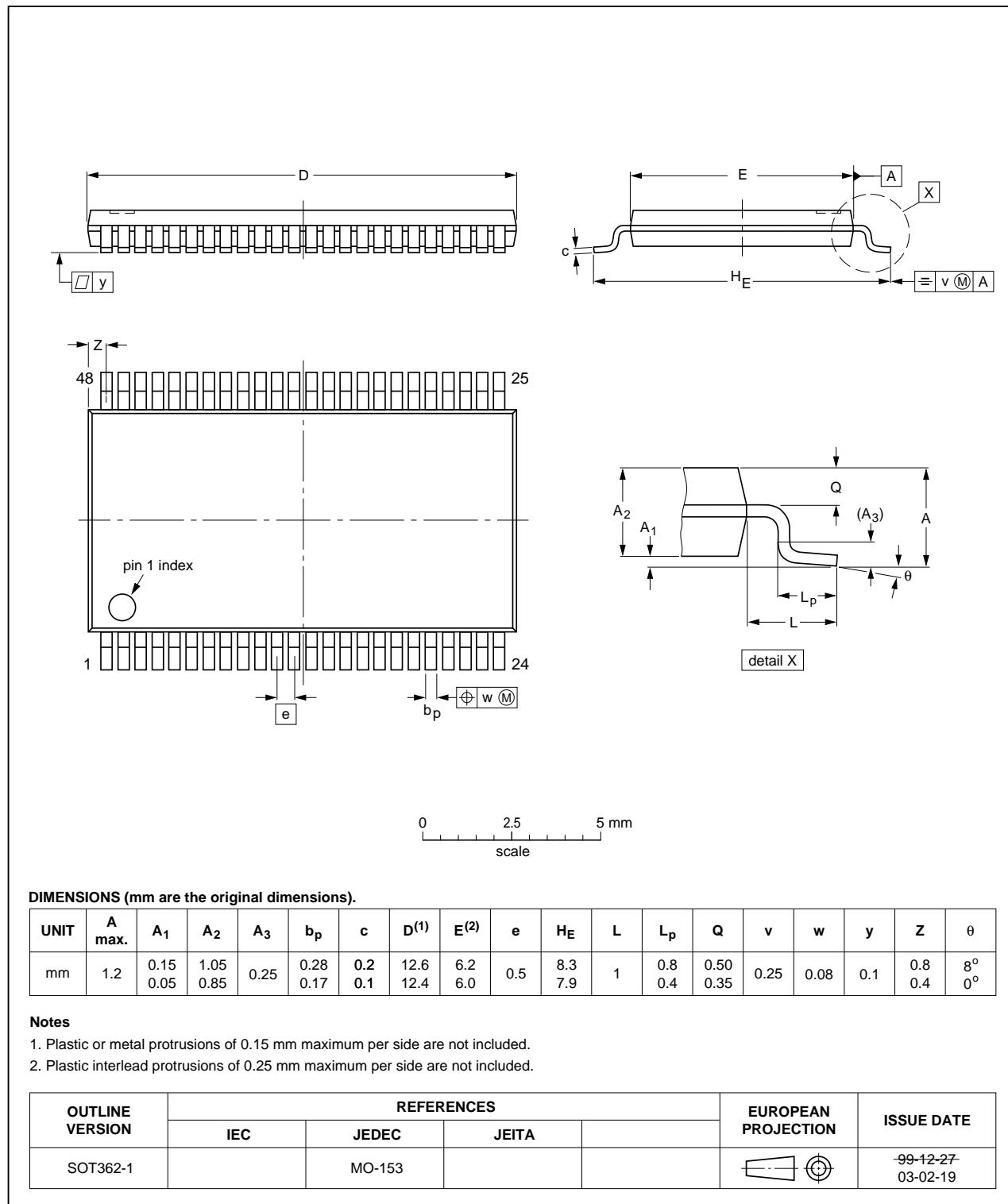


Fig 10. Package outline SOT362-1 (TSSOP48)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC16241A v.4	20111026	Product data sheet	-	74LVC16241A v.3
Modifications:			<ul style="list-style-type: none"> The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Table 4, Table 5, Table 6, Table 7, and Table 10: values added for lower voltage ranges. 	
74LVC16241A v.3	20040305	Product specification	-	74LVC16241A v.2
74LVC16241A v.2	19970729	Product specification	-	74LVC16241A v.1
74LVC16241A v.1	19951226	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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